OMB No. 0651-0011 (exp. 4/94)	PORT OF COMPART U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
Tab tsettings: t  To the Honorable Commissioner	02-27-2003  t t  ne attached original documents or copy
1. Name of conveying parties:  YASUHIKO SAKAKI  2.13.  Additional name(s) & party(ies) attached?	102375329  2. Name and address of receiving party(ies):  Name: Electroplating Engineers of Japan Ltd.  Internal Address:
3. Nature of conveyance:	Street Address: 6-6, Nihonbashikayaba-cho  2-chome, Chuo-ku, Tokyo 103-8206, Japan  City: State: Zip:  Additional name(s) & address(es) Yes X No attached?
is: A. Patent Application No.(s) /2003 DTESSEM1 00000008 10366302 :8021 40.00 GP	a new application, the execution date of the application  B. Patent No.(s)
, reducement deline	bers attached? Yes x No
Name and address of party to whom coconcerning document should be mailed Name:      Richard S. Roberts  Internal Address:  Roberts & Mercanti  Street Address:  P.O. Box 484	orrespondence 6. Total number of applications and patents involved:
Name and address of party to whom coconcerning document should be mailed Name:      Richard S. Roberts      Internal Address:      Roberts & Mercanti      Street Address:      P.O. Box 484      City: Princeton State: NJ Zip:	orrespondence d:  6. Total number of applications and patents involved:  1  7. Total fee (37 CFR 3.41)\$ 40.00  x Enclosed  Authorized to be charged to deposit account  8. Deposit account number:

Mail documents to be recorded with required cover sheet information to:

Commissioner for Patents, Box Assignments

Washington, D.C. 20231

PATENT REEL: 013777 FRAME: 0132

## **ASSIGNMENT**

WHEREAS the UNDERSIGNED, Yasuhiko SAKAKI, (and) citizen(s) of <u>JAPAN</u>, residing at <u>30-29 Kurobegaoka</u>, <u>Hiratsuka-shi</u>, <u>Kanagawa 254-0821</u>, <u>Japan</u>; has/have invented certain new and useful improvements (INVENTION) disclosed,

shown, and described in an APPLICATION for Letters Patent of the United States entitled:

## PLATING APPARATUS FOR WAFER

中10079-011111的議方位

said APPLICATION being executed concurrently herewith; and

WHEREAS,	Electroplating Engi	neers of Japan Limited		
a corporation of	Japan		, having an office at	
6-6, Nihonbashi	kayaba-cho 2-chome,	, Chuo-ku, Tokyo 103-8206, Japan		
(ASSIGNEE) is de	esirous of acquiring t	he entire right, title and interest in a	nd to the	
INVENTION, in this and any foreign country, and in and to any Letters Patent of the United				
States or any foreign	gn country which ma	y be granted embracing the INVEN	TION.	

NOW, THEREFORE, for and in consideration of One Dollar (\$1.00) and for other good and valuable consideration, receipt of which is hereby acknowledged, the UNDERSIGNED by these presents, sells, assigns, and transfers unto ASSIGNEE, its legal representatives, successors, and assigns, the entire right, title and interest for the United States and all foreign countries, in and to the INVENTION, and in and to the said APPLICATION, and in and to any applications for Letters Patent which may have been or may be filed in any foreign country on said INVENTION, and in and to any and all priority rights generated by the filing of said APPLICATION in the United States or any foreign country, which may be granted covering the INVENTION, including any continuations, continuations-in-part, substitutions, divisions, reissues or renewals thereof, said Letters Patent whether of this country or any foreign country to be held and enjoyed by ASSIGNEE for its interest, for its own use and behoof, and for its legal representatives, successors, and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by UNDERSIGNED had this assignment and sale not been made.

I covenant and agree that I will, at any time upon the request and at the expense of said ASSIGNEE, execute and deliver any and all papers and do all lawful acts that may be necessary or desirable, in the opinion of said ASSIGNEE, to enable and assist said ASSIGNEE to (a) obtain Letters Patent, both domestic and foreign, on said invention, (b) establish, maintain and secure title in said ASSIGNEE, its successors and assigns, to said invention, application and Letters Patent, including making such title of lawful public record, and (c) defend, establish or otherwise preserve the validity of said Letters Patent against any and all infringers, and perform such other acts as are necessary to give full force and effect to this assignment.

I hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent based on said application and all said divisions, continuations,

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continuations-in-part, reissues, renewals and extensions to said ASSIGNEE, its successors and assigns.

I authorize and empower the said ASSIGNEE, its successors, assigns and legal representatives or nominees, to invoke and claim for any application for patent or other form of protection for said inventions filed by it or them, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from me.

I hereby consent that a copy of this assignment shall be deemed a full and legal and formal equivalent of any assignment, consent to file or like document which may be required in any country for any purpose and more particularly in proof of the right of the said ASSIGNEE or nominee to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

IN WITNESS WHEREOF this assignment has been executed by UNDERSIGNED on the date opposite their name.

DATE 28 JAN 2003	Yasuhiko SAKAKI	Witness: Wutaka Kasuya
DATE		Witness:
DATE		Witness:

**RECORDED: 02/13/2003**